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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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#### CMLT2222AG

## SURFACE MOUNT SILICON **DUAL NPN TRANSISTOR**



• Device is Halogen Free by design



www.centralsemi.com

## **DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CMLT2222AG consists of two (2) isolated 2222A NPN silicon transistors, manufactured by the epitaxial planar process and epoxy molded in an SOT-563 surface mount package. These devices have been designed for small signal general purpose and switching applications.

**MARKING CODE: 2CG** 

MAXIMUM RATINGS: (T <sub>A</sub> =25°C)	SYMBOL		UNITS
Collector-Base Voltage	V <sub>CBO</sub>	75	V
Collector-Emitter Voltage	VCEO	40	V
Emitter-Base Voltage	$V_{EBO}$	6.0	V
Continuous Collector Current	$I_{\mathbb{C}}$	600	mA
Power Dissipation (Note 1)	$P_{D}$	350	mW
Power Dissipation (Note 2)	$P_{D}$	300	mW
Power Dissipation (Note 3)	$P_{D}$	150	mW
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	$^{\circ}C$
Thermal Resistance	$\Theta_{JA}$	357	°C/W

# **ELECTRICAL CHARACTERISTICS PER TRANSISTOR:** (TA=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I <sub>CBO</sub>	V <sub>CB</sub> =60V		10	nA
I <sub>CBO</sub>	V <sub>CB</sub> =60V, T <sub>A</sub> =125°C		10	μA
ICEV	$V_{CE}$ =60V, $V_{EB}$ =3.0V		10	nA
I <sub>EBO</sub>	V <sub>EB</sub> =3.0V		10	nA
BV <sub>CBO</sub>	I <sub>C</sub> =10μA	75		V
BVCEO	I <sub>C</sub> =10mA	40		V
BVEBO	I <sub>E</sub> =10μΑ	6.0		V
V <sub>CE</sub> (SAT)	I <sub>C</sub> =150mA, I <sub>B</sub> =15mA		0.3	V
VCE(SAT)	I <sub>C</sub> =500mA, I <sub>B</sub> =50mA		1.0	V
V <sub>BE</sub> (SAT)	I <sub>C</sub> =150mA, I <sub>B</sub> =15mA	0.6	1.2	V
V <sub>BE</sub> (SAT)	I <sub>C</sub> =500mA, I <sub>B</sub> =50mA		2.0	V
h <sub>FE</sub> ` ′	V <sub>CE</sub> =10V, I <sub>C</sub> =0.1mA	35		
h <sub>FE</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA	50		
hFE	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA	75		
hFE	V <sub>CE</sub> =1.0V, I <sub>C</sub> =150mA	50		
h <sub>FE</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =150mA	100	300	
h <sub>FE</sub>	$V_{CE}$ =10V, $I_{C}$ =500mA	40		

Notes: (1) Ceramic or aluminum core PC Board with copper mounting pad area of 4.0mm² (2) FR-4 Epoxy PC Board with copper mounting pad area of 4.0mm²

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<sup>(3)</sup> FR-4 Epoxy PC Board with copper mounting pad area of 1.4mm<sup>2</sup>

# CMLT2222AG

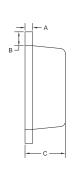


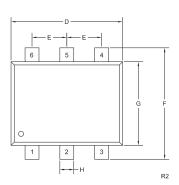


 $\textbf{ELECTRICAL CHARACTERISTICS PER TRANSISTOR - Continued:} \ (T_A = 25 ^{\circ}\text{C unless otherwise noted})$ 

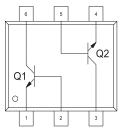
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
f <sub>T</sub>	V <sub>CE</sub> =20V, I <sub>C</sub> =20mA, f=100MHz	300		MHz
C <sub>ob</sub>	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1.0MHz		8.0	pF
C <sub>ib</sub>	V <sub>EB</sub> =0.5V, I <sub>C</sub> =0, f=1.0MHz		25	pF
h <sub>ie</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz	2.0	8.0	kΩ
h <sub>ie</sub>	$V_{CE}$ =10V, $I_{C}$ =10mA, f=1.0kHz	0.25	1.25	kΩ
h <sub>re</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz		8.0	x10 <sup>-4</sup>
h <sub>re</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=1.0kHz		4.0	x10 <sup>-4</sup>
h <sub>fe</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz	50	300	
h <sub>fe</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=1.0kHz	75	375	
h <sub>oe</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz	5.0	35	μS
h <sub>oe</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=1.0kHz	25	200	μS
rb'C <sub>C</sub>	V <sub>CB</sub> =10V, I <sub>E</sub> =20mA, f=31.8MHz		150	ps
NF	$V_{CE}$ =10V, $I_{C}$ =100mA, $R_{S}$ =1.0k $\Omega$ , f=1.0kHz		4.0	dB
$t_d$	V <sub>CC</sub> =30V, V <sub>BE</sub> =0.5, I <sub>C</sub> =150mA, I <sub>B1</sub> =15mA		10	ns
t <sub>r</sub>	V <sub>CC</sub> =30V, V <sub>BE</sub> =0.5, I <sub>C</sub> =150mA, I <sub>B1</sub> =15mA		25	ns
t <sub>s</sub>	V <sub>CC</sub> =30V, I <sub>C</sub> =150mA, I <sub>B1</sub> =I <sub>B2</sub> =15mA		225	ns
t <sub>f</sub>	V <sub>CC</sub> =30V, I <sub>C</sub> =150mA, I <sub>B1</sub> =I <sub>B2</sub> =15mA		60	ns

# **SOT-563 CASE - MECHANICAL OUTLINE**





DIMENSIONS					
	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	
A	0.0027	0.007	0.07	0.18	
В	0.008		0.20		
С	0.017	0.024	0.45	0.60	
D	0.059	0.067	1.50	1.70	
E	0.020		0.50		
F	0.059	0.067	1.50	1.70	
G	0.043	0.051	1.10	1.30	
Н	0.006	0.012	0.15	0.30	
SOT-563 (REV: R2)					



## LEAD CODE:

- 1) Emitter Q1
- 2) Base Q1
- 3) Collector Q2
- 4) Emitter Q2 5) Base Q2
- 6) Collector Q1

MARKING CODE: 2CG

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#### **OUTSTANDING SUPPORT AND SUPERIOR SERVICES**



#### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

#### **DESIGNER SUPPORT/SERVICES**

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- · Special wafer diffusions
- PbSn plating options
- · Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

#### REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

#### **CONTACT US**

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